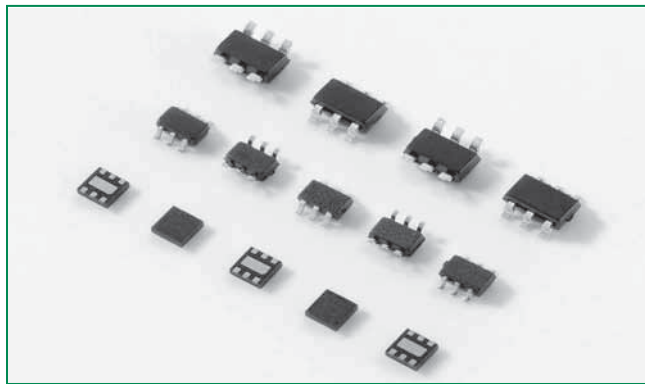
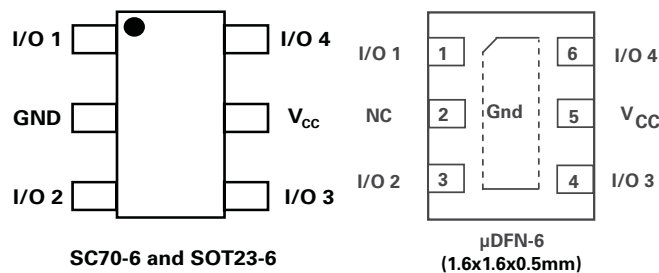


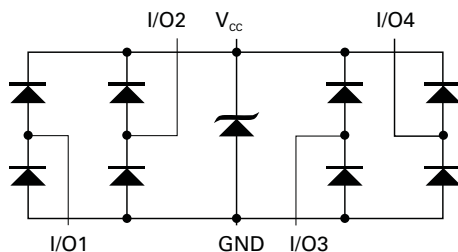
SP3002 Series 0.85pF Diode Array



Pinout



Functional Block Diagram



Description

The SP3002 has ultra low capacitance rail-to-rail diodes with an additional zener diode fabricated in a proprietary silicon avalanche technology to protect each I/O pin providing a high level of protection for electronic equipment that may experience destructive electrostatic discharges (ESD). These robust diodes can safely absorb repetitive ESD strikes at the maximum level (Level 4) specified in the IEC 61000-4-2 international standard without performance degradation. Their very low loading capacitance also makes them ideal for protecting high speed signal pins such as HDMI, DVI, USB2.0, and IEEE 1394.

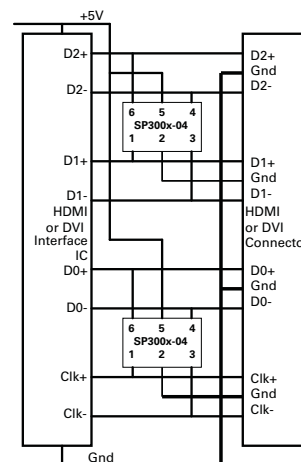
Features

- Low capacitance of 0.85 pF (TYP) per I/O
- ESD protection of $\pm 12\text{kV}$ contact discharge, $\pm 15\text{kV}$ air discharge, (IEC61000-4-2)
- EFT protection, IEC61000-4-4, 40A (5/50ns)
- Low leakage current of 0.5 μA (MAX) at 5V
- Small packaging options saves board space
- Lightning Protection, IEC61000-4-5, 4.5A (8/20 μs)

Applications

- Computer Peripherals
- Mobile Phones
- PDA's
- Digital Cameras
- Network Hardware/Ports
- Test Equipment
- Medical Equipment

Application Example



A single 4 channel SP300x-04 device can be used to protect four of the data lines in a HDMI/DVI interface. Two (2) SP300x-04 devices provide protection for the main data lines. Low voltage ASIC HDMI/DVI drivers can also be protected with the SP300x-04, the +V_{cc} pins on the SP300x-04 can be substituted with a suitable bypass capacitor or in some backdrive applications the +V_{cc} of the SP300x-04 can be floated or NC.

Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p=8/20\mu s$)	4.5	A
T_{OP}	Operating Temperature	-40 to 85	°C
T_{STOR}	Storage Temperature	-50 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

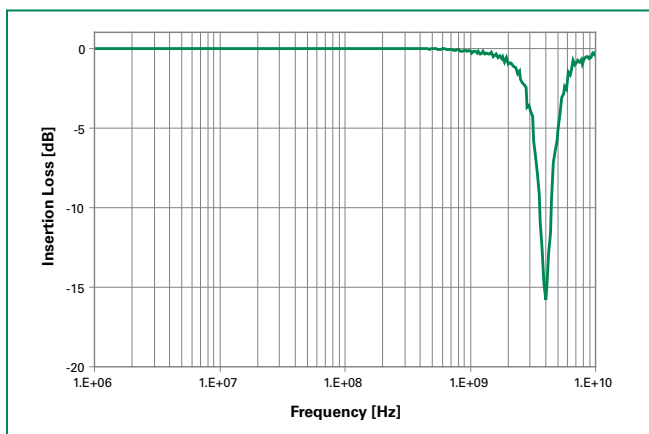
Parameter	Rating	Units
Storage Temperature Range	-65 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

Electrical Characteristics ($T_{OP}=25^{\circ}C$)

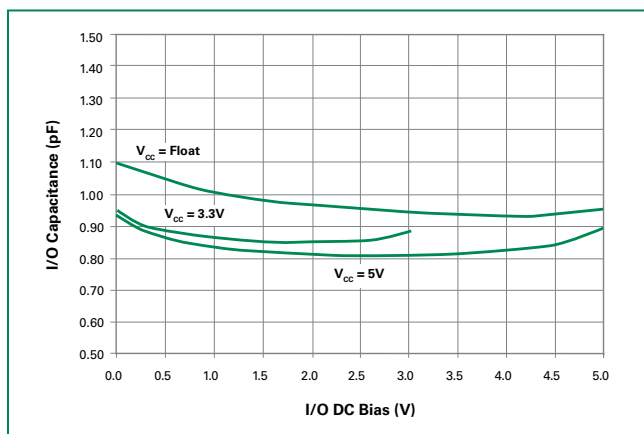
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}	$I_R \leq 1\mu A$			6.0	V
Reverse Leakage Current	I_{LEAK}	$V_R=5V$			0.5	μA
Clamp Voltage ¹	V_C	$I_{PP}=1A, t_p=8/20\mu s, Fwd$		9.5	11.0	V
		$I_{PP}=2A, t_p=8/20\mu s, Fwd$		10.6	13.0	V
ESD Withstand Voltage ¹	V_{ESD}	IEC61000-4-2 (Contact)	± 12			kV
		IEC61000-4-2 (Air)	± 15			kV
Diode Capacitance ¹	$C_{I/O-GND}$	Reverse Bias=0V	0.95	1.1	1.25	pF
		Reverse Bias=1.65V	0.7	0.85	1.0	pF
Diode Capacitance ¹	$C_{I/O-I/O}$	Reverse Bias=0V		0.5		pF

Note: 1. Parameter is guaranteed by design and/or device characterization.

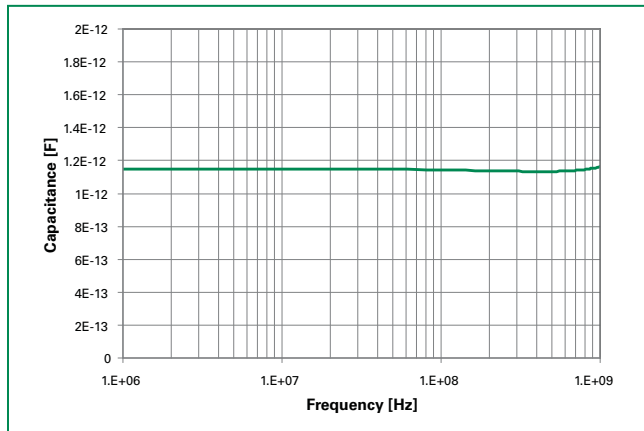
Insertion Loss (S21) I/O to GND



Capacitance vs. Bias Voltage



Capacitance vs. Frequency



Product Characteristics

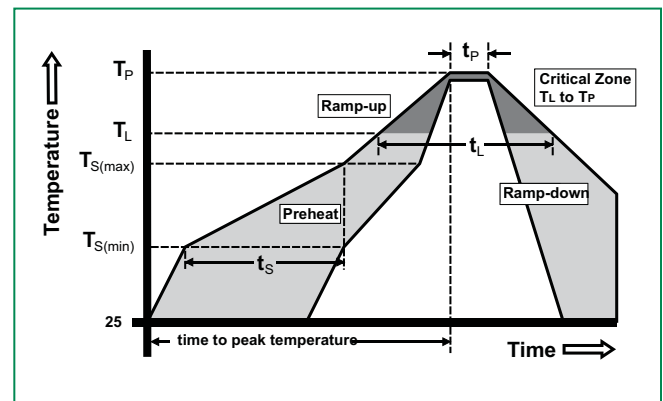
Lead Plating	SC70 & SOT23: Matte Tin μDFN: Pre-Plated Frame
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substrate Material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

Notes :

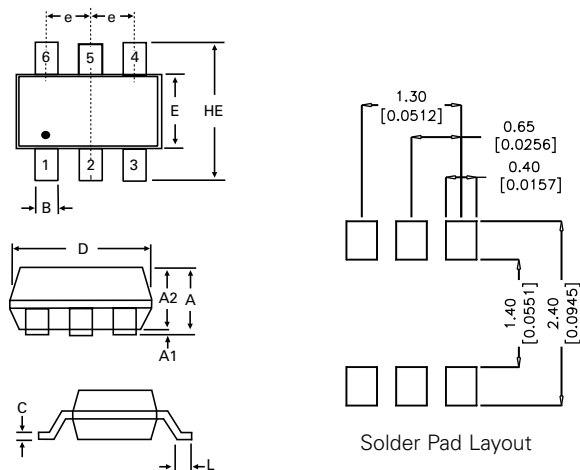
1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.

Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C

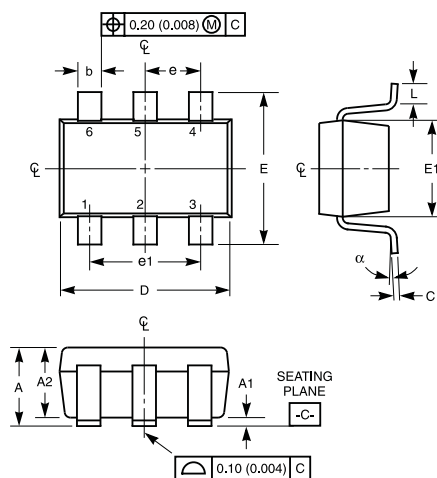


Package Dimensions — SC70-6

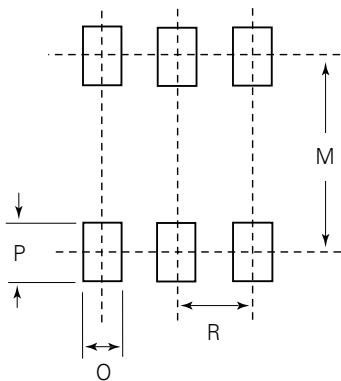


Package	SC70-6			
Pins	6			
JEDEC	MO-203			
	Millimeters		Inches	
	Min	Max	Min	Max
A	0.80	1.10	0.031	0.043
A1	0.00	0.10	0.000	0.004
A2	0.70	1.00	0.028	0.039
B	0.15	0.30	0.006	0.012
c	0.08	0.25	0.003	0.010
D	1.85	2.25	0.073	0.089
E	1.15	1.35	0.045	0.053
e	0.65 BSC		0.026 BSC	
HE	2.00	2.40	0.079	0.094
L	0.26	0.46	0.010	0.018

Package Dimensions — SOT23-6



Recommended Solder Pad Layout

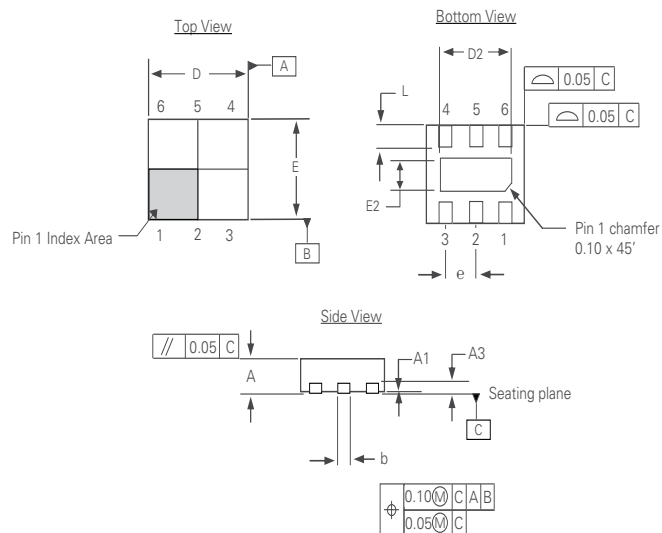


Package	SOT23-6			
Pins	6			
JEDEC	MO-178			
	Millimeters		Inches	
	Min	Max	Min	Max
A	0.900	1.450	0.035	0.057
A1	0.000	0.150	0.000	0.006
A2	0.900	1.300	0.035	0.051
b	0.350	0.500	0.0138	0.0196
C	0.080	0.220	0.0031	0.009
D	2.800	3.000	0.11	0.118
E	2.600	3.000	0.102	0.118
E1	1.500	1.750	0.06	0.069
e	0.95 Ref		0.0374 Ref	
e1	1.9 Ref		0.0748 Ref	
L	0.100	0.600	0.004	0.023
N	6		6	
a	0°	10°	0°	10°
M		2.590		0.102
O		0.690		.027 TYP
P		0.990		.039 TYP
R		0.950		0.038

Notes:

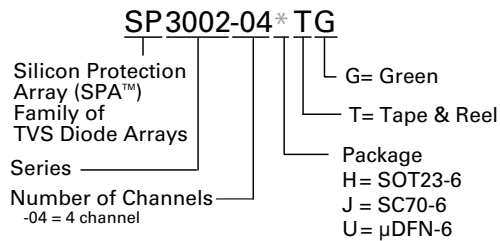
1. Dimensioning and tolerances per ANSI 14.5M-1982.
2. Package conforms to EIAJ SC-74 (1992).
3. Dimensions D and E1 are exclusive of mold flash, protrusions, or gate burrs.
4. Footlength L measured at reference to seating plane.
5. "L" is the length of flat foot surface for soldering to substrate.
6. "N" is the number of terminal positions.
7. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

Package Dimensions — μ DFN-6 (1.6x1.6x0.5mm)



Package	μ DFN-6 (1.6x1.6x0.5mm)			
JEDEC	MO-229			
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.45	0.55	0.018	0.022
A1	0.00	0.05	0.000	0.002
A3	0.127 Ref		0.005 Ref	
b	0.20	0.30	0.008	0.012
D	1.50	1.70	0.060	0.067
D2	1.05	1.30	0.042	0.052
E	1.50	1.70	0.060	0.067
E2	0.40	0.65	0.016	0.026

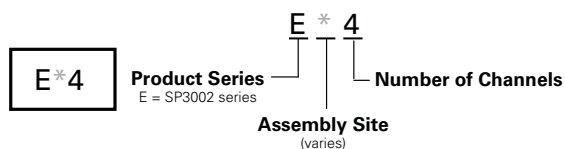
Part Numbering System



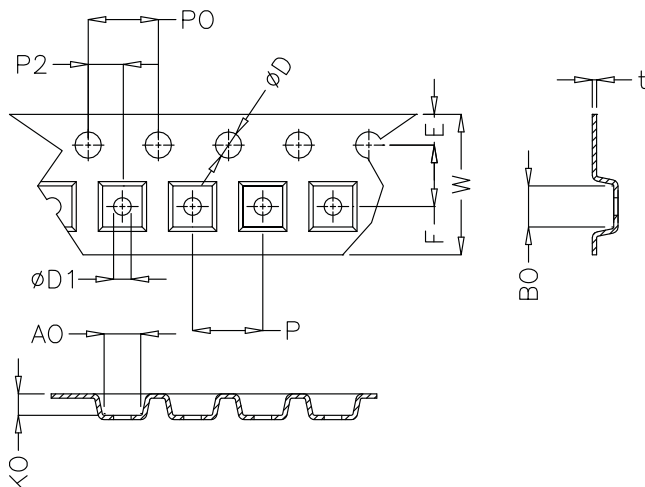
Ordering Information

Part Number	Package	Marking	Min. Order Qty.
SP3002-04HTG	SOT23-6	E*4	3000
SP3002-04JTG	SC70-6	E*4	3000
SP3002-04UTG	μ DFN-6 (1.6x1.6x0.5mm)	E*4	3000

Part Marking System



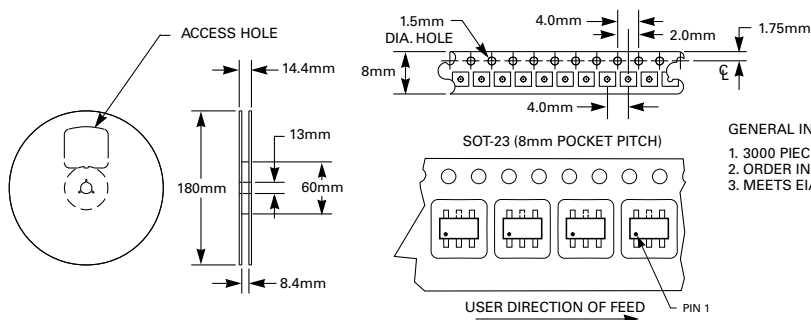
Embossed Carrier Tape & Reel Specification — SC70-6



Symbol	Millimetres		Inches	
	Min	Max	Min	Max
E	1.65	1.85	0.064	0.073
F	3.45	3.55	0.135	0.139
P2	1.95	2.05	0.077	0.081
D	1.40	1.60	0.055	0.063
D1	1.00	1.25	0.039	0.049
P0	3.90	4.10	0.154	0.161
10P0	40.0+/- 0.20		1.574+/-0.008	
W	7.70	8.10	0.303	0.318
P	3.90	4.10	0.153	0.161
A0	2.14	2.34	0.084	0.092
B0	2.24	2.44	0.088	0.096
K0	1.12	1.32	0.044	0.052
t	0.27 Max		0.010 Max	

Embossed Carrier Tape & Reel Specification — SOT23-6

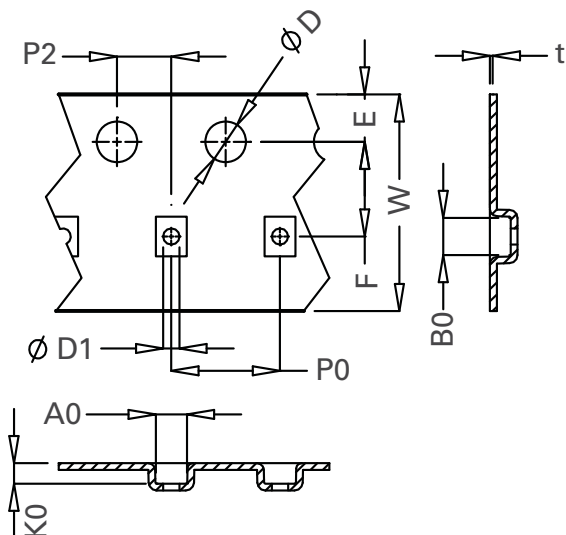
8mm TAPE AND REEL



GENERAL INFORMATION

1. 3000 PIECES PER REEL.
2. ORDER IN MULTIPLES OF FULL REELS ONLY.
3. MEETS EIA-481 REVISION "A" SPECIFICATIONS.

Embossed Carrier Tape & Reel Specification — µDFN-6 (1.6x1.6x0.5mm)



Symbol	Millimetres		Inches	
	Min	Max	Min	Max
E	1.65	1.85	0.06	0.07
F	3.45	3.55	0.14	0.14
D1	1.00	1.25	0.04	0.05
D	1.50 MIN		0.06 MIN	
P0	3.90	4.10	0.15	0.16
10P0	40.0+/- 0.20		1.57+/-0.01	
W	7.90	8.30	0.31	0.33
P2	1.95	2.05	0.08	0.08
A0	1.78	1.88	0.07	0.07
B0	1.78	1.88	0.07	0.07
K0	0.84	0.94	0.03	0.04
t	0.25 TYP		0.01 TYP	